

Claims

1. A method of interconnecting terminals characterized by including a terminal placement step of placing terminals so as to oppose each other with an anisotropic electrically conductive resin composition comprising at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles therebetween,
 - 5 a resin heating step of heating the anisotropic electrically conductive resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured, and
 - 10 a resin component curing step of curing the resin component.
2. A method of interconnecting terminals as set forth in claim 1
15 characterized in that in the resin heating step, the terminals are pressed towards each other with the anisotropic electrically conductive resin composition disposed therebetween.
3. A method of interconnecting terminals as set forth in claim 1
20 characterized in that the resin component is a resin having reducing properties which reduce at least one of the surface of the terminals and the surface of the electrically conductive particles.
4. A method of interconnecting terminals as set forth in claim 2
25 characterized in that the resin component is a resin having reducing properties which reduce at least one of the surface of the terminals and the surface of the electrically conductive particles.

5. A method of interconnecting terminals as set forth in any of claims 1 - 4 characterized in that in the terminal placement step, the anisotropic electrically conductive resin composition is supplied so as to achieve a state in which it completely fills the space between members on which the terminals are provided
5 including the space between opposing terminals.

6. A method of mounting a semiconductor device characterized by including an electrode placement step in which electrode pads of a semiconductor chip and circuit electrodes provided on a circuit substrate so as to correspond to
10 the electrode pads are placed opposite each other with an anisotropic electrically conductive resin composition comprising at least electrically conductive particles and a resin component therebetween,
a resin heating step in which the anisotropic electrically conductive resin composition is heated to a temperature higher than the melting point of the
15 electrically conductive particles and at which the resin component is not completely cured, and
a resin component curing step in which the resin component is cured.

7. A mounting method for a semiconductor device as set forth in claim 6
20 characterized in that in the electrode placement step, the anisotropic electrically conductive resin composition is supplied so as to achieve a state in which the anisotropic electrically conductive resin completely fills the space between the semiconductor chip and the circuit substrate including the space between the opposing electrode pads and circuit electrodes.